

Electronics Online Challenge

2020

iRobot Roomba 4220 Model Series



Team Name: MTSAC1 School: Mt. San Antonio College





Table of Contents

I. Introduction	3
II. Research	4
MC9S12E128CPV Microcontroller - Overview	4
Operating Characteristics	4
LM339 Quad Differential Comparator	5
JFET Operational Amplifier	6
Dirt Sensor	7
III. Conclusion	8
IV. References and Citations	9
Appendix A: iRobot Roomba Overview	. 12
Appendix B: Disassembly and Outer Anatomy	. 14
Home Base Disassembly	14
Virtual Wall	15
Motherboard	16
Front Bumper	17
Motor Encoder	18
Vacuum Intake	20
Appendix C: Parts Lists	. 21
List of Components - Sensors	21
List of Components - Integrated Circuits	22
List of Components - Other Components	24
Appendix D: Tables	32
Graph 1.1: Total IC Chip Count	32
Graph 1.2: Total IC count by Manufacturer	32
Graph 1.3: Total IC Count by Location	33
Graph 1.4: Total Component Count	33
Appendix E: MC9S12E128CPV Microcontroller Supporting Circuits	34
Package	34
Circuit Block Diagram	35
Central Processing Unit (CPU)	36
Memory	36
I/O Peripherals	36
Analog to Digital Converter (ADC)	. 37
Digital to Analog Converter (DAC)	. 37
Serial Interfaces	38
Serial Communication Interface (SCI)	39
Inter-Integrated Circuit (IIC).	39
Appendix F: Authors	40
Mt. San Antonio College Students	40
Jovany - Electrical Engineering Major	40
Michael - Computer Science Major	40
Thomas - Computer Science Major	40
Taha - Computer Science Major	41
Kimberly - Mechanical Engineering Maior.	41
Brandon - Electrical Engineering Major.	41

I. Introduction

The team, as seen in <u>Appendix F</u>, has chosen the Roomba 4220 because it is analogous to robots built for VEX Robotics Competition. For more information on the Roomba, see <u>Appendix</u> <u>A</u>. The engineers at iRobot built this device to accomplish specific tasks using programming and hardware while following strict constraints. Thus, our team chose this device to learn how other engineers have designed the circuitry to complete these tasks. Further, to discover how different circuit blocks contribute to the overall system. The device has been disassembled (see <u>Appendix</u> <u>B</u>), and all the electrical components have been cataloged (<u>Appendix C</u>), and the quantities of which were then tabulated (see <u>Appendix D</u>).



Fig. 1.1: Block Diagram showcasing how the six individual components connect to make up the Roomba.

Robol 10392 2004-05-31-1548 MC9512E128CPV 2L 15P 05-35 50 50 7

MC9S12E128CPV Microcontroller - Overview

Fig. 2.1: image of the MC9S12E128CPV, microcontroller (MCU) for the Roomba 4220, manufactured by Freescale Semiconductor.

The <u>MC9S12E128CPV</u> is designed to be a low cost general purpose MCU equipped with a 16-bit central processing unit (<u>HCS12 CPU</u>). It also includes other fundamental circuit blocks (see <u>Appendix E</u>) like Memory, I/O peripherals, serial ports, etc. Its role is to process information from <u>sensors</u>, control movement, and execute programming instructions.

Operating Characteristics



Fig. 2.2: Shows that the MC9S12E128CPV operates within -40C to 85C and that it is a 112-pin quad flat package.



Fig. 2.3: The differential comparator, LM339, is a device used to compare four pairs of voltage signals at a time.

There are four op-amps that compare the voltages of the inverting (-) and non-inverting (+) inputs. If the inverting input is greater, the output is drawn to the VCC power pin. If the non-inverting input is greater, the output is drawn to the GND power pin. In the <u>home base</u> charging dock, it supervises the power distributed to the Roomba. This works in collaboration with other electronic components in the home base (See <u>Appendix C</u>).





Fig. 2.4: There are 4 op-amps with 3 pins each that compares inputs, 2 pins for power, VCC and GND, that gives power to the chip.



Source: LM339 Quad Differential Comparator Data Sheet

Fig. 2.5: Each op-amp has an inverting and noninverting terminal that compares the voltage. Once voltage goes above the reference voltage, the outputs will power on.

JFET Operational Amplifier



Fig. 2.6: TL084C JFET-Input operational amplifier (op-amp) developed by Texas Instruments (TI) found upon disassembly of the <u>Vacuum Intake</u>. (See <u>Appendix B</u> for disassembly details)

The <u>TL084C JFET</u>-Input op-amp is an integrated circuit developed by Texas Instruments(TI) consisting of Junction-Gate Field Effect Transistors(JFETs) and Bipolar Transistors to change the input voltages into the desired output voltage. This op-amp boasts a high slew rate to allow minimal lag between the change in the input voltage and the resulting change for the output. For this reason, the op-amp is used in high precision applications such as the <u>dust sensor module</u> found in the Roomba.





Fig. 2.7: TL084 Pin Layout along with circuit schematic showcasing the Operational amplifier.

Dirt Sensor



Fig. 2.8: A picture of the dirt sensor (circular gold plate).

The <u>dirt sensor</u> controls the Roomba's vacuum intake. When driving over a dirty section of ground, the robot signals the brush roller motor to start spinning and pick up the dirt. This is possible because of the dirt sensor's piezoelectric properties.



Source: <u>Piezoelectric Property Explained</u> Fig. 2.9: Materials with piezoelectric properties generate small amounts of electricity when pressure is applied to them.

Source: <u>Roomba Brush Roller</u> Fig. 2.10: Vacuum brush roller.

When enough dirt particles hit the sensor, a current is generated and sent to the robot. If it's above a certain threshold the Roomba can assume that dirt is present, triggering the brush roller and starting the vacuum.

III. Conclusion

We learned that the Roomba implements the MC9S12E128CPV as the microcontroller, which enables it to interface with its sensors, motors, as well as execute program instructions. The LM339 regulates the charging of the Roomba via the home base. The dirt sensor detects dust particles, which informs the Roomba where to concentrate, thus making the machine more intelligent. Due to the vital role that electronic components play to provide efficient and optimal functionality, they are hand-picked during the engineering process. Thus, the meticulous planning displayed by the Roomba is a goal that we will match in our future work.

(Total Word Count: 493)

- Agarwal, Tarun. "IR Sensor Working and Its Interfacing with Microcontroller." *Edgefx Tech Official Blog*, 6 July 2015, www.edgefxkits.com/blog/ir-sensor-interfacing-withpic-microcontroller/.
- Brian Carlton. (1961, August 01). What is the difference between a general comparator and a differential comparator? Retrieved from https://electronics.stackexchange.com/questions/33961/what-is-the-difference-between-a-general-comparator-and-a-differential-comparato
- Contributors, T. (2019, November 07). What is a Microcontroller and How Does it Work? Retrieved December 03, 2020, from

https://internetofthingsagenda.techtarget.com/definition/microcontroller

- Cox, C., & Merrit, C. (2004). *Microcontroller Oscillator Circuit Design Considerations* [PDF]. Freescale Semiconductor, Inc.
- Gabay, Jon. "IR Technologies for Proximity Sensing." *DigiKey*, Electronic Products, 25 Apr. 2013, www.digikey.com/en/articles/ir-technologies-for-proximity-sensing.

Giovino, B. (2019, March 06). Know When and How to Choose and Apply an External DAC for a Microcontroller. Retrieved December 03, 2020, from https://www.digikey.com/en/articles/know-when-how-to-choose-apply-external-dac-formicrocontroller

"IR Sensor Module." *Components101*, 30 Aug. 2018, components101.com/sensors/ir-sensor-module.

LM339 Comparator IC Pinout, Examples Circuits, Datasheet, Applications. (2020, March 05). Retrieved from https://microcontrollerslab.com/lm339-quad-differential-comparator-ic/

LM339. (n.d.). Retrieved from https://www.ti.com/product/LM339

- Mahi, Devadas, J., Khubaib, Paracha, Z., Singh, K., J, A., . . . Jalaris. (2018, July 25). Basics of Microcontrollers - Structure, Applications, Pros & Cons. Retrieved December 03, 2020, from https://www.circuitstoday.com/basics-of-microcontrollers
- Mould, S. (2019, May 16). Piezoelectricity why hitting crystals makes electricity. https://youtu.be/wcJXA8IqY18.
- N3PF06 STN3PF06. Datasheet pdf. Equivalent. (n.d.). Retrieved from https://datasheetspdf.com/pdf/775350/STMicroelectronics/N3PF06/1
- Op-amp Comparator and the Op-amp Comparator Circuit. (2020, August 26). Retrieved December 02, 2020, from

https://www.electronics-tutorials.ws/opamp/op-amp-comparator.html

- Operational Amplifier Basics Op-amp tutorial. (2020, May 01). Retrieved December 02, 2020, from https://www.electronics-tutorials.ws/opamp/opamp_1.html
- Sharma, A. (2019, July). Piezoelectric Transducer Working Principle. https://www.yourelectricalguide.com/2019/07/piezoelectric-transducer-working-principle -applications-construction.html.
- Shawn. "All about Proximity Sensors: Which Type to Use?" *Latest Open Tech from Seeed Studio*, 19 Dec. 2019, www.seeedstudio.com/blog/2019/12/19/all-about-proximity-

sensors-which-type-to-use/.

TL084. (n.d.). Retrieved December 03, 2020, from https://www.ti.com/product/TL084

TL08xx FET-Input Operational Amplifiers. (n.d.). Retrieved December 02, 2020, from https://www.ti.com/lit/ds/symlink/tl084.pdf?ts=1606925467563&ref_url=https%253A%25 2F%252Fwww.ti.com%252Fproduct%252FTL084%253FHQS%253DTI-null-null-alldatas heets-df-pf-SEP-wwe%2526DCM%253Dyes%2526dclid%253DCMq96bS_re0CFYzd4Qo dydcH9Q





Home Base Disassembly		
Isometric View	Front View	Top-Down View
	Robot	Band Band Band Band Band Band Band Band
Step 1: Use a screwdriver to	Step 2: Once screws are	Step 3: Remove loose screws
loosen screws.	plastic piece.	pull grey plastic piece, and expose the interior.
Step 4: Unscrew around circuit board.	Step 5: Remove surrounding parts anchoring circuit board.	Step 6: Gently pull the circuit board out.

Virtual Wall		
Isometric View	Bottom View	Battery Storage View
	<text></text>	
Step 1: The virtual wall unit consists of an On/Off button, range selection and infrared light.	Step 2: Remove one screw to open the battery storage.	Step 3: Take out the four rubber stands and unscrew four nuts to look at the interior unit.
Step 4: Unscrew 6 more screws that are connected to the PCB.	Step 5: Turn the circuit board over to view the bottom portion.	Step 6: Rotate the bottom circuit board to access the side components.

Motherboard		
Top-Down View	Underside View	Top-Down View
Step 1: When removing the top, disconnect all ribbon cables that connect to the motherboard.	Step 2: Remove 4 screws that strap down the motherboard to the chassis.	Step 3: Push the back bumper in and lift to remove it.

Front Bumper		
Isometric View	Front View	Top-Down View
Step 1: Remove 2 screws and take off springs to detach the bumper off of the enclosure.	Step 2: Remove the 4 enclosures within the bumper which are holding in the IR proximity sensors.	Step 3: IR emitter and receiver can be isolated by pulling the 2 plastic enclosures apart.

Motor Encoder		
Isometric View	Front View	Outer-Side View
Step 1: Remove back plate cover.	Step 2: Unscrew pins holding DC Motor in place.	Step 3: Remove DC Motor.



Vacuum Intake		
Isometric View	Front View	Outer-Side View
Contraction of the second seco		J. Start
Step 1: Unscrew Dirt Sensor housing.	Step 2: Remove PCB cover.	Step 3: Lift PCB case off of vacuum intake.
Step 4: Take PCB out of case.	Step 5: Desolder PCB from wires.	Step 6: Flip over to have isolated dirt sensor.

Appendix C: Parts Lists

List of Components - Sensors		
Description / Location	Picture	
IR Signal Emitter - Front Bumper		
(Figure C1) An LED that emits infrared signals which bounce off of objects, used for distance tracking.		
IR Photo Diode Sensor - Front Bumper		
(Figure C2) An LED that only receives infrared signals that have bounced off of objects determining the distance based on angles.		
Dirt Sensor - Attached to the inward side of the vacuum intake		
(Figure C3) A piezoelectric sensor that detects large patches of dirt and triggers vacuum to start.		
Optical Wheel Encoder System		
(Figure C4) Keeps track of the revolutions turned by counting the times a gear has blocked light coming from an LED to a photosensor	A CONTRACTOR OF THE OF	

List of Components - Integrated Circuits		
Chip / Description / Manufacturer	Picture	Datasheet URL
63CYLFK-LM339 - Quad Comparator Texas Instruments (Figure C4) 4 independent voltage comparators, compares signals and can shift voltage.		https://www.ti.com/lit/ds/symlink/1 m2901.pdf?ts=1604675293288&ref _url=https%253A%252F%252Fww w.google.com%252F
MC9S12E128 - Microcontroller NXP Semiconductor (Figure C5) Microcontrollers are typically compact integrated circuits (IC's) designed to perform specific functions or tasks within larger embedded systems.		http://www.farnell.com/datasheets/2 295660.pdf?_ga=2.117078662.1677 503991.1603779458-622760620.16 03779458

L7805CVCC1F9 - Voltage Regulator -STMicroelectronics

(Figure C6)

A three-terminal positive voltage regulator with an output current up to 1.5A and output voltages up to 24V.

L7805CV.pdf



TL084C - Quad Operational Amplifier -Texas Instruments

(Figure C7)

A high-speed JFET input, quad operational amplifier incorporating well matched, high voltage JFET and bipolar transistors in a monolithic integrated circuit.



https://www.ti.com/lit/ds/symlink/tl 084.pdf?HQS=TI-null-null-mouser mode-df-pf-null-wwe&ts=16051629 82224&ref_url=https%253A%252F %252Fwww.mouser.com%252F

78L05 - Positive Voltage Regulator -STMicroelectronics

(Figure C8) A 3 terminal positive regulator whose purpose is to regulate the voltage within a given application.



https://pdf1.alldatasheet.com/datash eet-pdf/view/22687/STMICROELE CTRONICS/78L05.html

List of Components - Other Components		
Description	Picture	
MMBT4401L (2X) - Transistor		
(Figure C9) An NPN-type switching transistor designed for automotive and other general purpose applications.		
Data Sheet: https://www.mouser.com/datasheet/2/308/MMBT44 01LT1-D-108598.pdf		
30CA - Diode		
(Figure C10) A transient voltage suppression diode that is designed to protect circuits from high voltage transients. Data Sheet: <u>SMBJ 30 CA, 600W, SMD SMC</u>		
(transient voltage suppressor diodes)		

S8050 - NPN Silicon Transistor - Unisonic Technologies CO. LTD

(Figure C11)

A low voltage high current small signal NPN type transistor that is designed for audioamplication and for general purpose application.

Data Sheet:

https://components101.com/sites/default/files/compo nent_datasheet/S8050%20Transistor%20Datasheet.p df TD S8050

S8550 -PNP Epitaxial Silicon Transistor -Unisonic Technologies CO. LTD

(Figure C12)

A low voltage high current small signal NPN type transistor that is designed for Class B push-pull audio amplifiers and general purpose applications.

Manufacturer: Unisonic Technologies CO. LTD

Data Sheet: https://datasheetspdf.com/pdf/576673/UTC/S8550/1





JST-XH Connector

(Figure C13)

A variety of general purpose JST connectors to combine electrical conductors and create electrical circuits.

Data Sheet: http://www.jst-mfg.com/product/pdf/eng/eXH.pdf?5f a50d346228b

N3PF06Y628 - Power MOSFET -STMicroelectronics - Motherboard

(Figure C14)

Power MOSFET with a maximum Drain-Source Voltage (Vdss) of 60V, a maximum drain current of 2.5 A, and max on-resistance of 0.22 Ohms.

Data Sheet: https://www.mouser.com/datasheet/2/389/stn3pf06-9 56389.pdf





B772 - PNP Epitaxial Silicon Transistor - Unisonic Technologies CO. LTD	
(Figure C15) A low voltage medium power transistor, which is designed for DC-DC Conversion, Voltage regulation, and Audio Amplification. Compliment to 2SD882.	
https://pdf1.alldatasheet.com/datasheet-pdf/view/333 70/UTC/B772.html	
D882 - NPN Silicon Transistor - Unisonic Technologies CO. LTD	
(Figure C16) This transistor can handle output current up to 2A, features a low saturation voltage, and it is a complement to the existing 2SB772 Transistor. Data Sheet: https://datasheet4u.com/datasheet-pdf/UTC/D882/pd	
Surface Mount Resistor	042
(Figure C17) A rectangular ceramic body which has conductive leads on each end. Similar to a traditional resistor with it's ohmic value printed on the front.	

Through Hole Resistor

(Figure C18)

An electronic component, designed to limit the flow of electrons, that has a constant electrical resistance value.



Quartz Crystal Oscillator

(Figure C19)

A high Q resonant component that generates sinusoidal signals as a response to an initial voltage change.

R37

Through Hole Electrolytic Capacitor

(Figure C20)

Capacitor which uses a high-ion concentrated liquid, known as an electrolytic, as its dielectric to store energy within an electric field.



Surface Mount Capacitor

(Figure C21)

Ceramic capacitor typically used in high frequency applications. Dielectric materials used have very high dielectric constants such as Titanium Dioxide and Barium Titanate.



Surface Mount Tantalum Capacitor

(Figure C22)

Tantalum capacitors achieve high capacitance values through the use of a tantalum pentoxide dielectric, a large plate area, and a thin dielectric thickness.



Zener Diode

(Figure C23)

Zener diodes constrain current to only flow from anode to cathode. Except for when a voltage threshold is met, Zener voltage.



Schottky Diode

(Figure C24)

A semiconductor diode which features low turn-on voltage, fast recovery time, and a low junction capacitance. Ideal for high frequency circuits.



Brush Roller Motor

(Figure C25)

This internal motor controls the vacuum brush roller that picks dirt up off of the ground. Activated by the dirt sensor.



Battery Pack

(Figure C26)

Nickel Metal Hydride battery pack responsible for powering the entire Roomba by supplying 14.4 volts.





Graph 1.1: Total IC Chip Count

Fig. D1: Bar chart displaying integrated chip counts organized by chip types.



Graph 1.2: Total IC count by Manufacturer

Fig. D2: Bar chart displaying integrated chip counts organized by manufacturer.



Graph 1.3: Total IC Count by Location

Fig. D4: Bar chart displaying total integrated circuit counts organized by their location in the Roomba.



Graph 1.4: Total Component Count

Fig. D5: Bar chart displaying total electronic component counts organized by component names.

Appendix E: MC9S12E128CPV Microcontroller Supporting Circuits



Package

Fig. E1: The pinout for the 112 connections available for this variant of the MC9S12.



Circuit Block Diagram

Fig. E2: This shows the numerous integrated circuits that enable the MC9S12E128CPV to execute tasks and take in data from sensors.

Central Processing Unit (CPU)

BKGD 🔸	MODC/ Single-w	TAGHI ire Background	CPU12
XFC -	Deb	ug Module	Periodic Interrupt
EXTAL ->	CPC	Clock and	Clock Monitor
XTAL -	Und	Generation	Debugger(DBG12)
RESET			Breakpoints

Source: MC9S12E128CPV Datasheet

Fig E3: The HC12, a derivative of the 68HC11 by Motorola, is used for processing instructions through simple arithmetics, I/O, and logic operations.

Memory



Source: MC9S12E128CPV Datasheet

Fig. E4: The MC9S12E128CPV contains 128K Bytes Flash EEPROM to store program data and it has 8K Bytes RAM for temporary data storage.

I/O Peripherals





Analog to Digital Converter (ADC)

ADC	AN0 AN1 AN2 AN2 AN4 AN4 AN5 AN6 AN7 AN8 AN9	KWAD0 KWAD1 KWAD2 KWAD3 KWAD4 KWAD5 KWAD6 KWAD6 KWAD7 KWAD8 KWAD9		PAD0 PAD1 PAD2 PAD3 PAD3 PAD4 PAD5 PAD6 PAD7 PAD8 PAD9
	AN10 AN10 AN11 AN12 AN13 AN13 AN14 AN15	KWAD10 KWAD11 KWAD12 KWAD13 KWAD14 KWAD15	+ + + + +	\rightarrow PAD10 \rightarrow PAD10 \rightarrow PAD11 \rightarrow PAD12 \rightarrow PAD13 \rightarrow PAD14 \rightarrow PAD15

Source: MC9S12E128CPV Datasheet

Fig. E6: The ADC within the MCU allows for communication between external analog devices by converting analog waveforms into digital signals.

Digital to Analog Converter (DAC)



Fig. E7: The inverse of the ADC, which allows the MCU to create custom analog signals for frequency or voltage generations.

Serial Interfaces



Source: MC9S12E128CPV Datasheet

Fig E8: Shows the location of the Serial Communication Interfaces (SCI), Serial Peripheral Interface (SPI), and the Inter-Integrated Circuit (IIC).



Serial Communication Interface (SCI)

Source: MC9S12E128CPV Datasheet

Fig. E9: The SCI above allows full-duplex, asynchronous, serial communication between the CPU and the external devices.

Inter-Integrated Circuit (IIC)





Appendix F: Authors

Mt. San Antonio College Students				
Name / Contribution	Picture			
Jovany - Electrical Engineering Major (Figure F1) Jovany worked on the <u>motherboard</u> and the <u>microcontroller</u> . Further, he worked on assembling the <u>parts lists</u> , and he led the team.	eden of respect			
Michael - Computer Science Major (Figure F2) Michael focussed on the motor module and the <u>motor</u> <u>encoders</u> . Additionally, he researched the <u>JFET</u> <u>Operational Amplifier</u> .				
Thomas - Computer Science Major (Figure F3) Thomas contributed to researching the dirt sensor and the vacuum intake. Further, he assisted in proof-reading and in formatting the report.				

Taha - Computer Science Major (Figure F4) Taha contributed by studying the virtual wall along with all the components inside of it. Additionally, he helped with creating the disassembly procedures.	
Kimberly - Mechanical Engineering Major (Figure F4) Kimberly helped by taking apart the <u>home base</u> along with researching the LM339 Differential Comparator. She Created the Tables seen in <u>Appendix D</u> .	
Brandon - Electrical Engineering Major (Figure F4) Brandon worked on the <u>front bumper</u> along with formatting the report. He also helped with putting together the <u>parts list</u> .	